Formation Mechanism of Voids and Pin-holes in CuSbS₂ Thin Film

via Sulfurizing Co-sputtered Cu-Sb Precursor

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Fig S1 Temperature profiling of sulfurization process and photographs of samples as indicated on temperature profiling.

Samples	Compositions	PDF Cards #
Precursor	Cu Cu2Sb	01-070-3038 01-085-0492
	Sb	01-085-1322
200 °C	$egin{array}{c} { m Cu} & \ { m Cu_2S} & \ { m Cu_2Sb} & \ { m Sb} & \ \end{array}$	01-070-3038 00-002-1284 01-085-0492 01-085-1322
250 °C	CuS Sb	00-024-0060 01-085-1322
300 °C	CuS Sb_2S_3 Sb	00-024-0060 01-075-1310 01-085-1322
350 ℃	$\begin{array}{c} CuS\\ Sb_2S_3\\ Sb\end{array}$	00-024-0060 01-075-1310 01-085-1322
370 °C	$\begin{array}{c} CuS\\ CuSbS_2\\ Sb_2S_3 \end{array}$	00-024-0060 03-065-2416 01-075-1310
380 °C	$CuSbS_2$ Sb_2S_3	03-065-2416 01-075-1310
380 °C-3min	$CuSbS_2$ Sb_2S_3	03-065-2416 01-075-1310

Table S1 Summary of phase evolution of Cu-Sb co-sputtering precursor after being sulfurized at a series of temperatures and times.



Fig S2 SEM and corresponding EDS mapping images of Cu-Sb precursor after sulfurization treatment at 350 °C followed by rapid cooling.



Fig S3 Microscopy analysis of Cu-Sb precursor after sulfurization treatment at 250 °C followed by rapid cooling, (a) cross-section TEM image, (b) STEM-EDS mapping, (c) phases mapping, (d) STEM-EDS line scan as arrow marked in (c), (e) SEM image of exfoliated backside surface.



Fig. S4 Schematic diagram of the thin film morphology and the corresponding Pillings-Bedworth ratio.

For a general solid reaction,

$$aA_{(s)} + b B_{(s)} \rightarrow c C_{(s)} + d D_{(s)}$$

the $\ensuremath{\text{PB}_{\text{ratio}}}$ can then be expressed as

$$PB_{ratio} = \frac{\sum_{i} v_i [M_i / \rho_i]_{product}}{\sum_{i} v_i [M_i / \rho_i]_{reactant}}$$

where *i* denotes the compound, v_i is the stoichiometric coefficient of *i*, M_i represents the molar mass of *i* in (g/mol), and ρ_i is the density of *i* in (g/cm³).

	ρ (g/cm ³)	M (g/mol)	Reaction	PB-ratio
Cu	8.96	63.546		
Sb	6.697	121.76		
S	2.07	32.066		
Cu_2S	5.6	159.158	$2Cu + S(g) \rightarrow Cu_2S$	2.00
CuS	4.76	95.611	$Cu + S(g) \rightarrow CuS$	2.83
Sb_2S_3	4.562	339.715	$2Sb + 3S(g) \rightarrow Sb_2S_3$	2.05
$CuSbS_2$	4.87	249.43	$2CuS + Sb_2S_3 \rightarrow 2CuSbS_2 + S(g)$	0.89
			$2Cu + Sb_2S_3 \rightarrow 2CuSbS_2$	1.16
			$Cu_2S + Sb_2S_3 \rightarrow 2CuSbS_2$	1

 Table S2 Densities and molar masses for the various elements and compounds, as well as the Pillings

 Bedworth ratios calculated for the given reactions.



Fig S5 Microscopy analysis of Cu-Sb precursor after sulfurization treatment at 380 °C followed by rapid cooling, (a) cross-section TEM image, (b) STEM-EDS mapping, (c) phases mapping, (d) STEM-EDS line scan as arrow marked in (c).

Sample ID	Cu/Sb	Sb loss (%)
precursor	0.889	N/A
350 °C	0.896	0.713
380 °C	0.904	1.630
380 °C-3min	0.906	1.796

Table S3 Composition changes of $CuSbS_2$ thin films subjected to different sulfurization treatments measured by ICP.